# **IEEE COMPUTER SOCIETY ANNUAL SYMPOSIUM ON VLSI**

## **CALL FOR PAPERS**

www.isvlsi2018.org

## July 9-11, 2018 Hong Kong, China















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Hong Kong Univ. of Sci. and Tech., China

City University of Hong Kong, China

Hong Kong Polytechnic University

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■ Hai Li.

Duke University, USA

■ Yu Wang,

Tsinghua University, China

■ Wuiie Wen.

Florida International Univ., USA

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The Chinese Univ. of Hong Kong, China

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Nanyang Technological Univ., Singapore

■ Zheng Wang, Shenzhen Institutes of Advanced Technology of the Chinese Academy of Science

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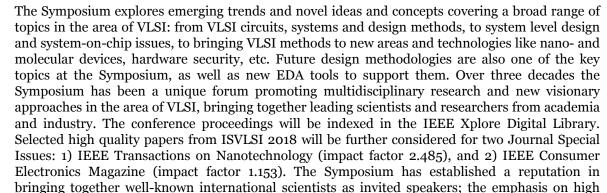
■ Wei Zhang,

Hong Kong Univ. of Sci. and Tech., China

■ Jürgen Becker, Karlsruhe Institute of Tech., Germany

Tongji University, China

■ Zhihong Wu,



### Contributions are sought in the following areas

quality will continue at this and future editions of the Symposium.

- 1) Analog and Mixed-Signal Circuits (AMS): Analog/mixed-signal circuits, RF and communication circuits, adaptive circuits, interconnects, VLSI aspects of sensor and sensor network.
- 2) Computer-Aided Design and Verification (CAD): Hardware/software co-design, logic and behavioral synthesis, simulation and formal verification, physical design, signal integrity, power and thermal analysis, statistical approaches.
- 3) Digital Circuits and FPGA based Designs (DCF): Digital circuits, chaos/neural/fuzzy-logic circuits, high speed/low-power circuits, energy efficient circuits, near and sub-threshold circuits, memories, FPGA designs, FPGA based systems.
- 4) Emerging and Post-CMOS Technologies (EPT): Nanotechnology, molecular electronics, quantum devices, optical computing, spin-based computing, biologically-inspired computing, CNT, SET, RTD, QCA, reversible logic, and CAD tools for emerging technology devices and circuits.
- 5) System Design and Security (SDS): Structured and Custom Design methodologies, microprocessors/micro-architectures for performance and low power, embedded processors, analog/digital/mixed-signal systems, NoC, power and temperature aware designs, Hardware security, Cryptography, watermarking, and IP protection, TRNG and security oriented circuits, PUF circuits.
- 6) Testing, Reliability, and Fault-Tolerance (TRF): Analog/digital/mixed-signal testing, design for testability and reliability, online testing techniques, static and dynamic defect- and faultrecoverability, and variation aware design.

The Symposium Program will include contributed papers and speakers invited by the Program Committee as well as a poster session. The keynotes, special sessions and Student Research Forum are planned as well. Authors are invited to submit full-length, original, unpublished papers. To enable blind review, the author list should be omitted from the main document. Initial submissions to the conference are limited to six pages in PDF format.

## **Paper Submission Deadlines**

Paper Submission Deadline: March 4th, 2018 (Final Extension)

Acceptance Notification: April 2, 2018 Submission of Final Version: May 12, 2018 Special Session Proposal Deadline: March 2, 2018